

TOSHIBA INFRARED LED GaAs INFRARED EMITTER

TLN113

INFRARED LED FOR PHOTO SENSOR

Unit in mm

OPTO-ELECTRONIC SWITCH

TAPE, CARD READERS

ROTARY ENCODER

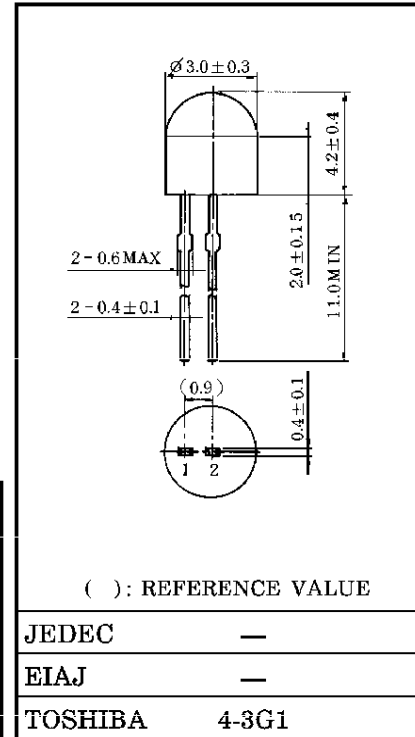
DETECTION OF FDD (FLOPPY DISK DRIVE)

- High radiant intensity
- Best suited for combination with Photo Transistor TPS613.

MAXIMUM RATINGS (Ta = 25°C)

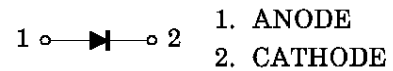
CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current	I_F	40	mA
Forward Current Derating (Ta > 25°C)	$\Delta I_F / ^\circ C$	-0.53	mA / °C
Pulse Forward Current (Note)	I_{FP}	400	mA
Reverse Voltage	V_R	5	V
Operating Temperature Range	T_{opr}	-20~75	°C
Storage Temperature Range	T_{stg}	-30~100	°C

(Note) Pulse Width $\leq 100\mu s$, Repetitive Frequency = 100Hz



Weight : 0.08g (TYP.)

PIN CONNECTION



OPTO-ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V_F	$I_F = 10mA$	—	1.15	1.30	V
Reverse Current	I_R	$V_R = 5V$	—	—	10	μA
Radiant Intensity (Note)	I_E	$I_F = 20mA$	0.8	—	4.8	mW / sr
Radiant Power	P_o	$I_F = 20mA$	—	2.5	—	mW
Capacitance	C_T	$V_R = 0, f = 1MHz$	—	30	—	pF
Peak Emission Wavelength	λ_P	$I_F = 20mA$	—	940	—	nm
Spectral Line Half Width	$\Delta\lambda$	$I_F = 20mA$	—	50	—	nm
Half Value Angle	$\theta_{\frac{1}{2}}$	$I_F = 20mA$	—	± 40	—	°

(Note) I_E classification AB : 0.8~3.0mW / sr, BC : 1.25~4.8mW / sr, A : 0.8~2.0mW / sr
B : 1.25~3.0mW / sr, C : 2.0~4.8mW / sr

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● TOSHIBA is continually working to improve the quality and the reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to observe standards of safety, and to avoid situations in which a malfunction or failure of a TOSHIBA product could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent products specifications. Also, please keep in mind the precautions and conditions set forth in the TOSHIBA Semiconductor Reliability Handbook.

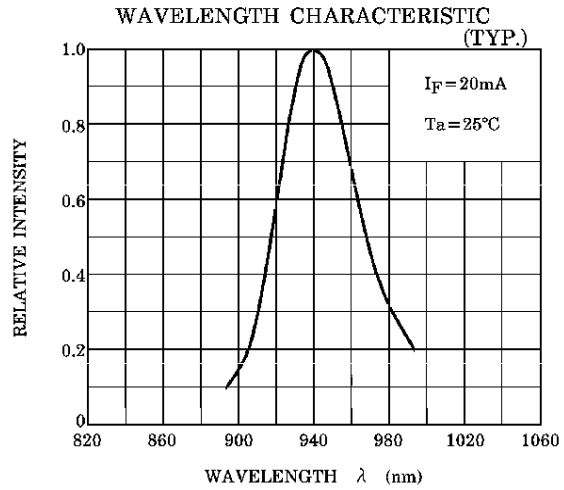
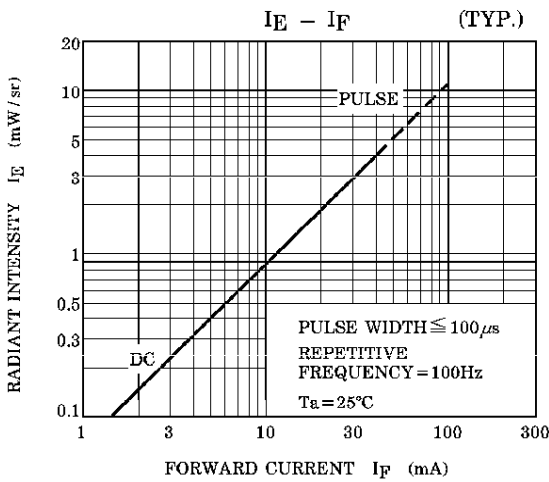
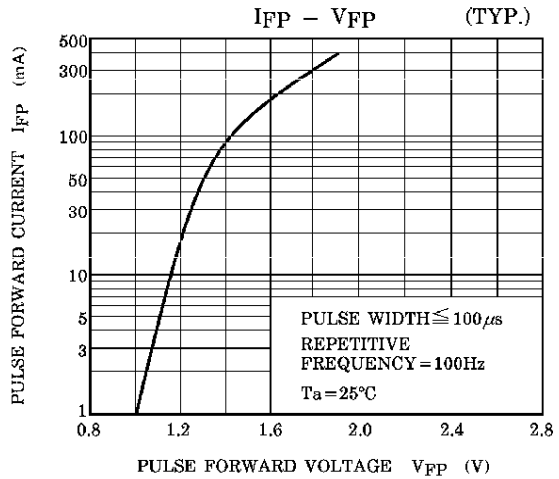
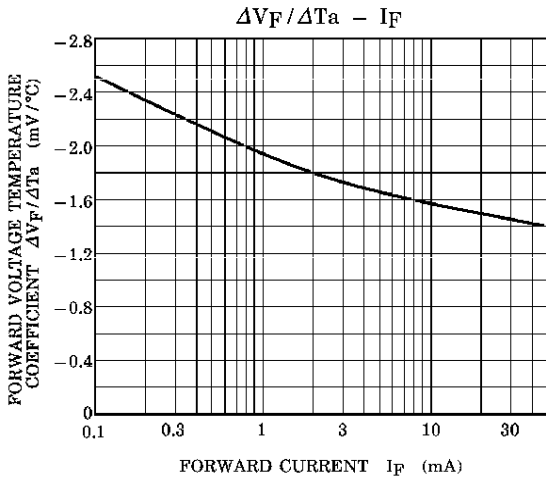
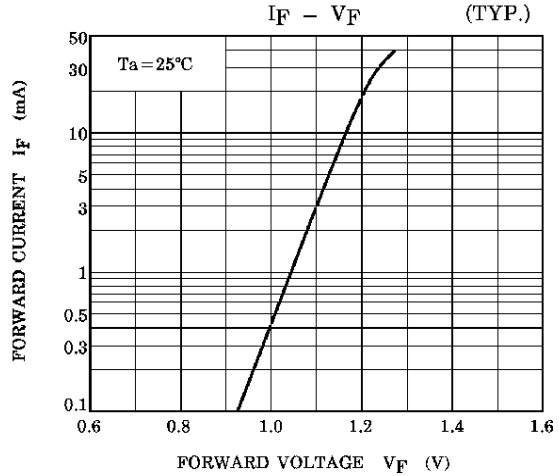
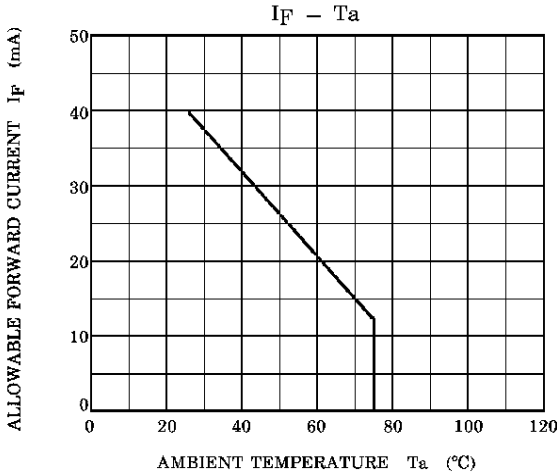
PRECAUTION

Please be careful of the followings.

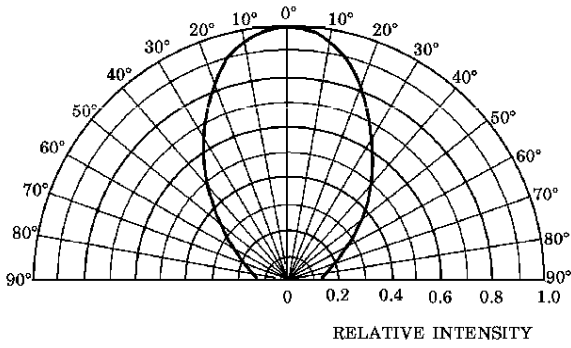
1. Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
(Soldering portion of lead : above 2mm from the body of the device)
2. When the lead is formed, the lead shall be formed at a distance of 2mm from the body without leaving forming stress to the body of the device.
Soldering shall be performed after lead forming.

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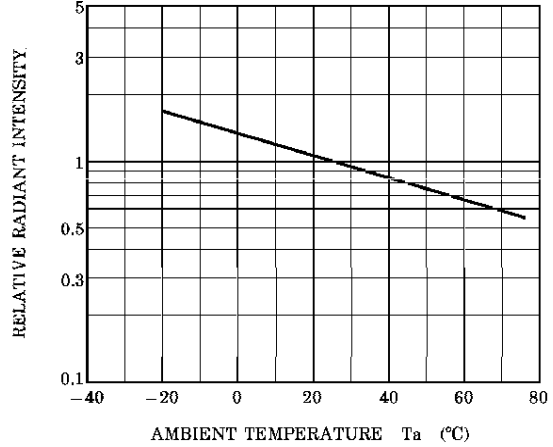
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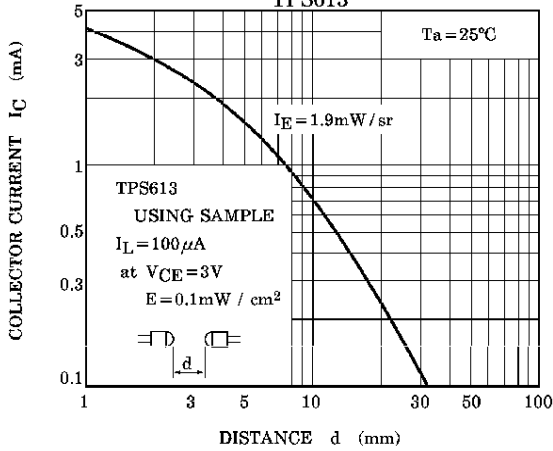
RADIATION PATTERN (TYP.)
($T_a = 25^\circ\text{C}$)



RELATIVE $I_E - T_a$ (TYP.)



COUPLING CHARACTERISTIC WITH TPS613



$I_{FP} - P_W$

